

#### 1.6X1.25mm BI-COLOR SMD CHIP LED LAMP

Part Number: APTB1612ESGC-F01

High Efficiency Red Super Bright Green

#### **Features**

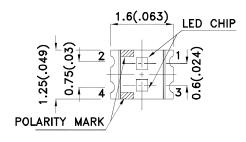
- 1.6mmx1.25mm SMT LED, 0.65mm thickness.
- Bi-color,low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

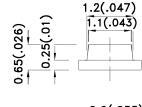
#### **Description**

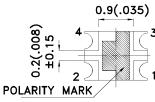
The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

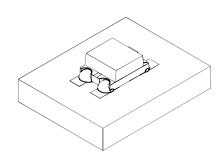
The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

#### **Package Dimensions**









#### Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.2(0.008") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
- 4. The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAF1097 REV NO: V.7A

APPROVED: WYNEC CHECKED: Allen Liu

DATE: MAR/16/2013 DRAWN: F.Cui PAGE: 1 OF 6 ERP: 1203002009

#### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APTB1612ESGC-F01	High Efficiency Red (GaAsP/GaP)	- Water Clear	8	15	120°
			*3	*7	
	Super Bright Green (GaP)		5	12	
			*5	*12	

- Notes:
  1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
  2. Luminous intensity/ luminous Flux: +/-15%.

  \* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	High Efficiency Red Super Bright Green	627 565		nm	I==20mA	
λD [1]	Dominant Wavelength	High Efficiency Red Super Bright Green	617 568		nm	I=20mA	
Δλ1/2	Spectral Line Half-width	High Efficiency Red Super Bright Green	45 30		nm	IF=20mA	
С	Capacitance	High Efficiency Red Super Bright Green	15 15		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	High Efficiency Red Super Bright Green	2 2.2	2.5 2.5	V	IF=20mA	
lR	Reverse Current	High Efficiency Red Super Bright Green		10 10	uA	VR = 5V	

#### Notes:

- 1.Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.

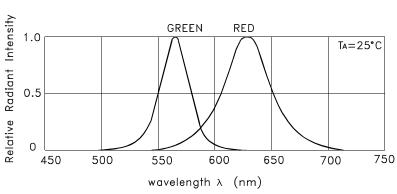
  3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

### Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Super Bright Green	Units		
Power dissipation	75	62.5	mW		
DC Forward Current	30	25	mA		
Peak Forward Current [1]	160	140	mA		
Reverse Voltage		V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

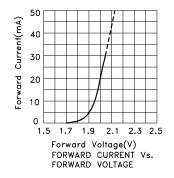
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

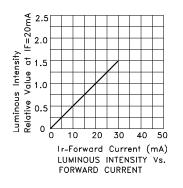
SPEC NO: DSAF1097 **REV NO: V.7A** DATE: MAR/16/2013 PAGE: 2 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** ERP: 1203002009 DRAWN: F.Cui

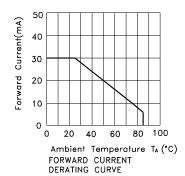


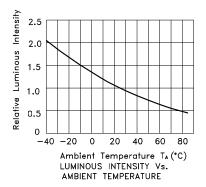
RELATIVE INTENSITY Vs. WAVELENGTH

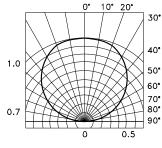
### APTB1612ESGC-F01 High Efficiency Red









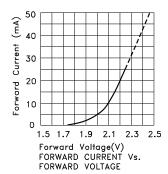


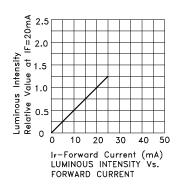
SPATIAL DISTRIBUTION

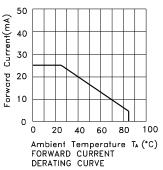
 SPEC NO: DSAF1097
 REV NO: V.7A
 DATE: MAR/16/2013
 PAGE: 3 OF 6

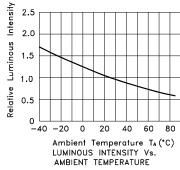
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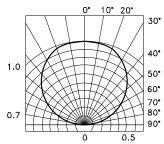
### **Super Bright Green**











SPATIAL DISTRIBUTION

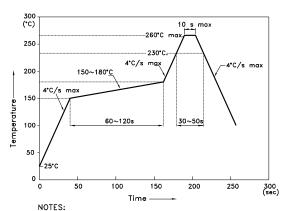
 SPEC NO: DSAF1097
 REV NO: V.7A
 DATE: MAR/16/2013
 PAGE: 4 OF 6

 APPROVED: WYNEC
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 ERP: 1203002009

#### APTB1612ESGC-F01

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

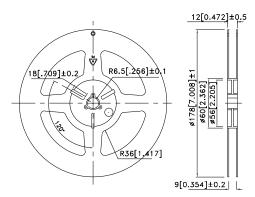
  2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

  3.Number of reflow process shall be 2 times or less.

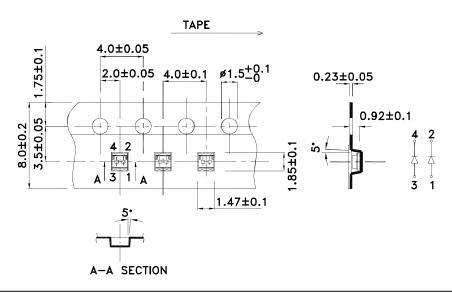
#### **Recommended Soldering Pattern** (Units: mm; Tolerance: ± 0.1)

# 0.86 1.65

## **Reel Dimension**



**Tape Dimensions** (Units: mm)



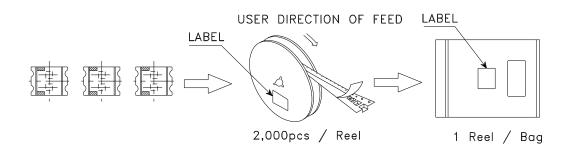
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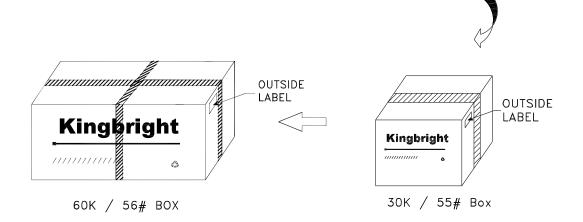
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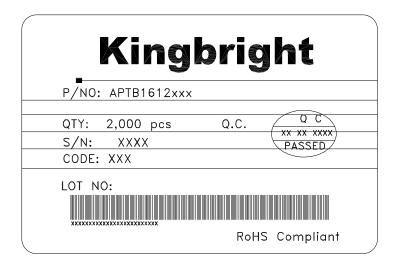
PAGE: 5 OF 6 ERP: 1203002009

#### **PACKING & LABEL SPECIFICATIONS**

#### APTB1612ESGC-F01







All design applications should refer to Kingbright application notes available at <a href="http://www.KingbrightUSA.com/ApplicationNotes">http://www.KingbrightUSA.com/ApplicationNotes</a>

SPEC NO: DSAF1097 APPROVED: WYNEC REV NO: V.7A CHECKED: Allen Liu DATE: MAR/16/2013 DRAWN: F.Cui PAGE: 6 OF 6 ERP: 1203002009